

L Number	Hits	Search Text	DB	Time stamp
2	2	((thermal adj adhesive) and (heat adj sink)) and (pre-cured post-cured)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 12:34
3	2	((thermal adj adhesive) and (heat adj sink)) and pre-cured	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 12:36
4	1	(thermal adj adhesive) and (heat adj sink)	USOCR	2003/11/13 12:36
1	168	(thermal adj adhesive) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 15:04
5	7	((thermal adj adhesive) and (heat adj sink)) and (cured near3 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 13:05
6	0	((thermal adj adhesive) and (heat adj sink)) and (pre-hardened near3 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 13:05
7	1	((thermal adj adhesive) and (heat adj sink)) and (hardened near3 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 13:05
8	16	((thermal adj adhesive) and (heat adj sink)) and spacer\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 13:11
11	156	(thermal adj epoxy) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 15:05
12	143	((thermal adj epoxy) and (heat adj sink)) not ((thermal adj adhesive) and (heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 15:57

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